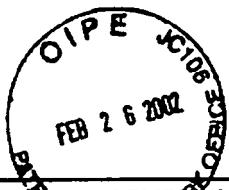




Date: February 15, 2002
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Form PTO-1449 (REV. 07/01) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO. INDUM-108XX	APPLICATION NO. 10/008,853	
INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				APPLICANT: Wusheng Yin, et al.		
				FILING DATE 11/15/01		GROUP 2811
				U.S. PATENT DOCUMENTS		
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*
(PJ)	5,128,746	7/7/92	Pennisi et al	357	72	
(PJ)	6,038,136	3/14/00	Weber	361	783	
(PJ)	6,157,086	12/5/00	Weber	257	788	
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
(PJ)	WO 99/56312	11/4/99				
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)						
(PJ)	A Novel Approach to Incorporate Silica Filler into No-Flow Underfill, Zhuqing Zhang, et al., School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, pp. 1-7.					
(PJ)	No Flow Underfill Materials for Environment Sensitive Flip-Chip Process, A Dissertation Presented to The Academic Faculty, Zhuqing Zhang, Georgia Institute of Technology, June 2001, pp. 1-125.					
(PJ)	"No-Flow" Underfill Reliability is Here – Finally!, Michael A. Previti, Cookson Semiconductor Packaging Materials, Alpharetta, GA, Session P-MT1, pp. 1-4.					
(PJ)	The Development of No-Flow Underfill Materials for Flip-Chip Applications, Advisor Dr. C.P. Wong, Student S.H. Shi, School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, February 2, 1999.					
EXAMINER	<i>Zhuqing Zhang</i>			DATE CONSIDERED		<i>11/15/01</i>
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						



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INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				APPLICANT: Wusheng Yin, et al.				
				FILING DATE 11/16/01		GROUP 2811		
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*		
FOREIGN PATENT DOCUMENTS3								
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	YES	NO
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)								
<i>AT</i>	Surface Mount Technology, Materials, Processes and Equipment, Carment Capillo, UNISYS Corporation, Network Computing Group, San Jose, CA, McGraw-Hill Publishing Co.							
<i>AT</i>	Epoxy Flip Chip Flux PK-001, Indium Corporation of America, Form No. 97727 R0.							
<i>AT</i>	Pb-Free Epoxy Flip Chip Flux PK-002, Indium Corporation of America, Form No. 97728 R0.							
EXAMINER	<i>Janet A. Reinke</i>			DATE CONSIDERED			<i>7/15/03</i>	
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

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